

Electronic Patent Application Fee Transmittal

Application Number:	10581162
Filing Date:	31-Mar-2008
Title of Invention:	Wire-Bonded Semiconductor Component with Reinforced Inner Connection Metallization
First Named Inventor/Applicant Name:	Jorg Behrens
Filer:	Mark Alan Wilson
Attorney Docket Number:	DE03 0414 US1

Filed as Large Entity

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Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Request for continued examination	1801	1	810	810
Total in USD (\$)				810